

Abstract of the Disclosure:

A method for producing an electronic component, includes producing a standardized lead frame having a predetermined number of leads that can be used with any one of a plurality of integrated circuits having different base areas. The standardized lead frame is produced with an island having a predetermined maximum base area for supporting any one of the plurality of integrated circuits. One of the plurality of integrated circuits is selected. The base area of the island is reduced, in accordance with a base area of the selected integrated circuit, to obtain a ratio between the base area of the selected integrated circuit and the base area of the island of from 0.7 to 0.9. The selected integrated circuit is fixed on the island, and the selected integrated circuit and the island are embedded in a casting or molding compound so that a unit formed by the selected integrated circuit and the island is substantially vertically centered within the casting or molding compound. An electronic component produced by the method is also provided in which flexure of the housing is reduced.

MPW/bb